

74F574

Octal D-Type Flip-Flop with 3-STATE Outputs

General Description

The 74F574 is a high-speed, low power octal flip-flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$). The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

This device is functionally identical to the 74F374 except for the pinouts.

Features

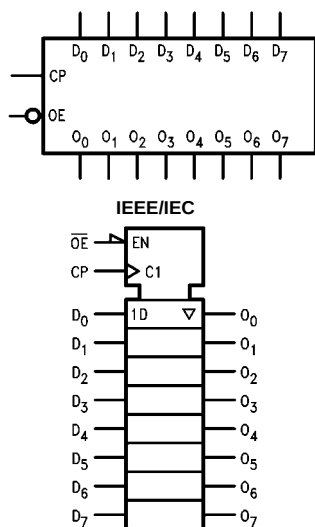
- Inputs and outputs on opposite sides of package allowing easy interface with microprocessors
- Useful as input or output port for microprocessors
- Functionally identical to 74F374
- 3-STATE outputs for bus-oriented applications

Ordering Code:

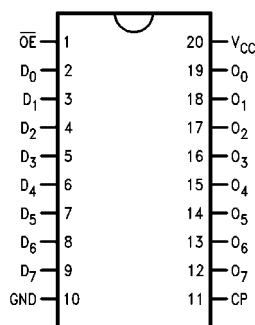
Order Number	Package Number	Package Description
74F574SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F574SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F574PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
D ₀ –D ₇	Data Inputs	1.0/1.0	20 μ A/–0.6 mA
CP	Clock Pulse Input (Active LOW)	1.0/1.0	20 μ A/–0.6 mA
$\overline{OE}$	3-STATE Output Enable Input (Active LOW)	1.0/1.0	20 μ A/–0.6 mA
O ₀ –O ₇	3-STATE Outputs	150/40 (33.3)	–3 mA/24 mA (20 mA)

Functional Description

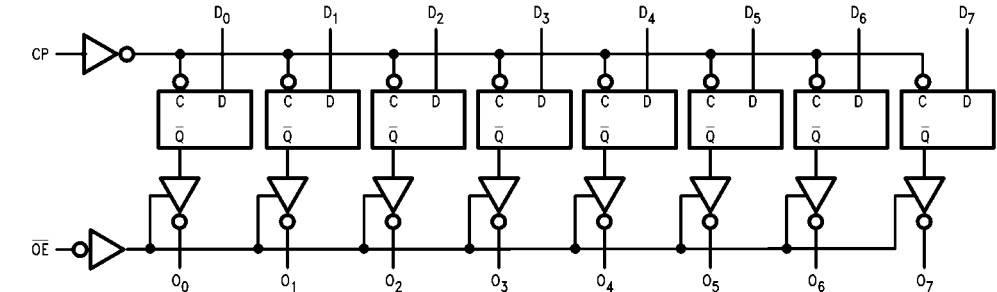
The 74F574 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold times requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

Function Table

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	$\nearrow$	L	L	Z	Load
H	$\nearrow$	H	H	Z	Load
L	$\nearrow$	L	L	L	Data Available
L	$\nearrow$	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance
 $\nearrow$ = LOW-to-HIGH Transition
 NC = No Change

Logic Diagram



Absolute Maximum Ratings(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with V_{CC} = 0V)Standard Output -0.5V to V_{CC}

3-STATE Output -0.5V to +5.5V

Current Applied to Output

in LOW State (Max) twice the rated I_{OL} (mA)**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

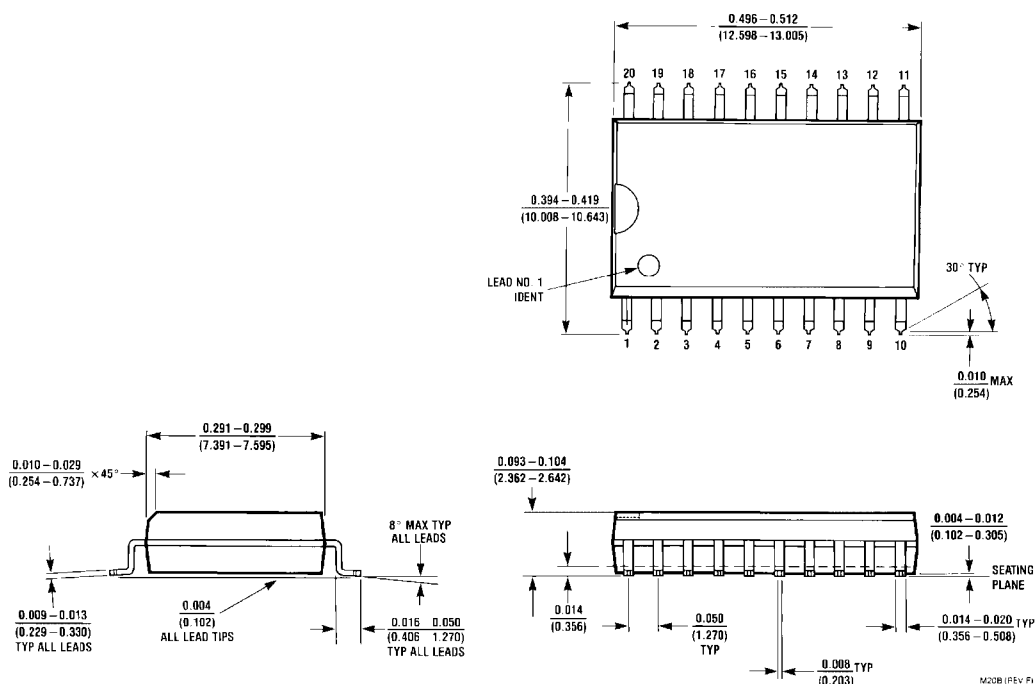
Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	10% V _{CC} 10% V _{CC} 5% V _{CC} 5% V _{CC}	2.5 2.4 2.7 2.7		V	Min	I _{OH} = -1 mA I _{OH} = -3 mA I _{OH} = -1 mA I _{OH} = -3 mA
V _{OL}	Output LOW Voltage	10% V _{CC}		0.5	V	Min	I _{OL} = 24 mA
I _{IH}	Input HIGH Current			5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{ID} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V
I _{OZH}	Output Leakage Current			50	μA	Max	V _{OUT} = 2.7V
I _{OZL}	Output Leakage Current			-50	μA	Max	V _{OUT} = 0.5V
I _{OS}	Output Short-Circuit Current	-60		-150	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μA	0.0V	V _{OUT} = 5.25V
I _{CCZ}	Power Supply Current		55	86	mA	Max	V _O = HIGH Z

AC Electrical Characteristics

Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = -55°C to +125°C V _{CC} = +5.0V C _L = 50 pF		T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t _{MAX}	Maximum Clock Frequency	100			60		70		MHz
t _{PLH}	Propagation Delay	2.5	5.3	8.5	2.5	9.5	2.5	8.5	ns
t _{PHL}	CP to O _n	2.5	5.3	8.5	2.5	9.5	2.5	8.5	
t _{PZH}	Output Enable Time	3.0	5.5	9.0	2.5	10.5	2.5	10.0	ns
t _{PZL}		3.0	6.0	9.0	2.5	10.5	2.5	10.0	
t _{PHZ}	Output Disable Time	1.5	3.3	5.5	1.5	7.0	1.5	6.5	
t _{PLZ}		1.5	2.8	5.5	1.5	7.0	1.5	6.5	

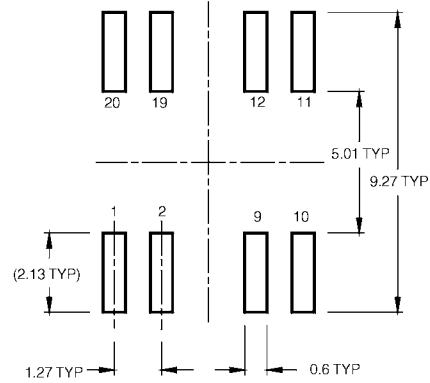
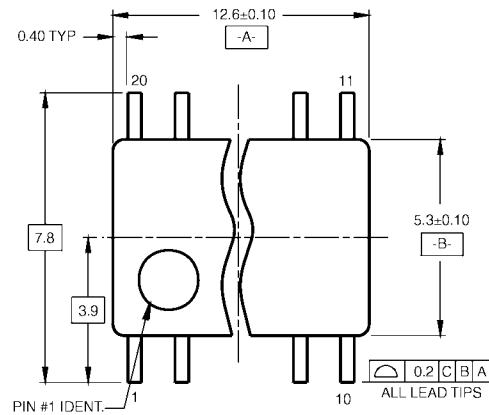
AC Operating Requirements

Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V		T _A = -55°C to +125°C V _{CC} = +5.0V		T _A = 0°C to +70°C V _{CC} = +5.0V		Units
		Min	Max	Min	Max	Min	Max	
t _S (H)	Set-up Time, HIGH or LOW	2.5		3.0		2.5		ns
t _S (L)	D _n to CP	2.0		2.5		2.0		
t _H (H)	Hold Time, HIGH or LOW	2.0		2.0		2.0		
t _H (L)	D _n to CP	2.0		2.0		2.0		
t _W (H)	CP Pulse Width	5.0		5.0		5.0		ns
t _W (L)	HIGH or LOW	5.0		5.0		5.0		

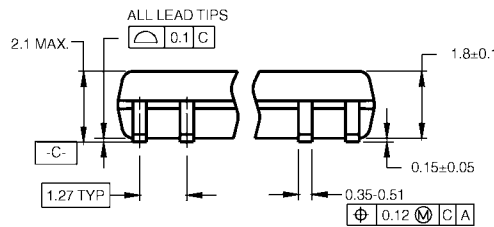
Physical Dimensions inches (millimeters) unless otherwise noted


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B**

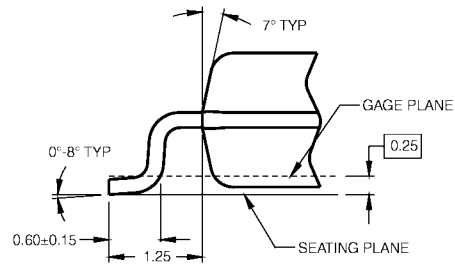
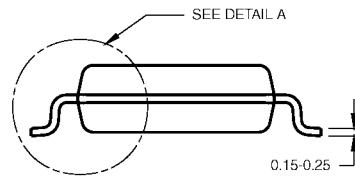
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

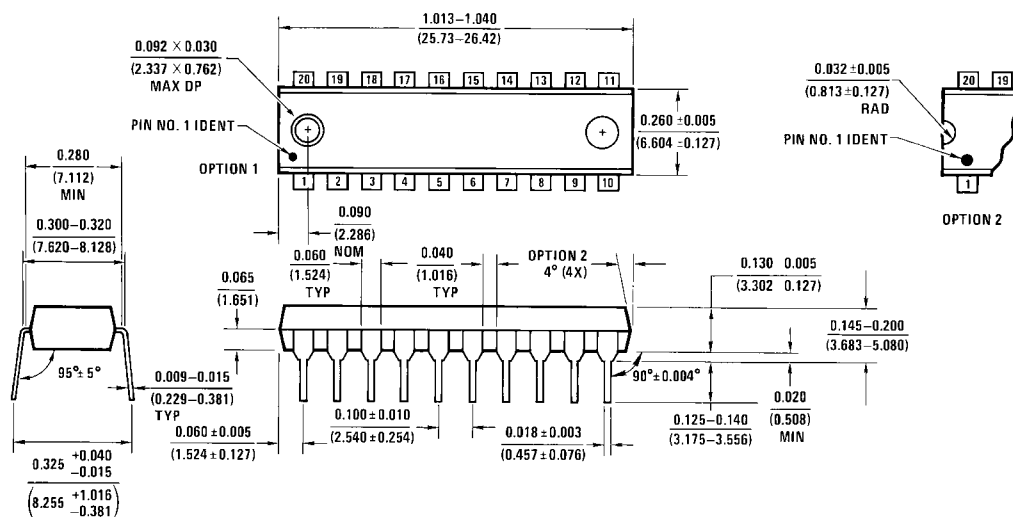
NOTES:

- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N20A**

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